

SOT2036-1

BGA388, ball grid array package, 388 terminals, 0.56 mm pitch, 15 mm x 15 mm x 2.09 mm body

10 October 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA388
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	24-07-2019
Manufacturer package code	98ASA01460D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	14.85	15	15.15	mm
package width	14.85	15	15.15	mm
seated height	1.94	2.09	2.24	mm
nominal pitch	-	0.56	-	mm
actual quantity of termination	-	388	-	



2 Package outline

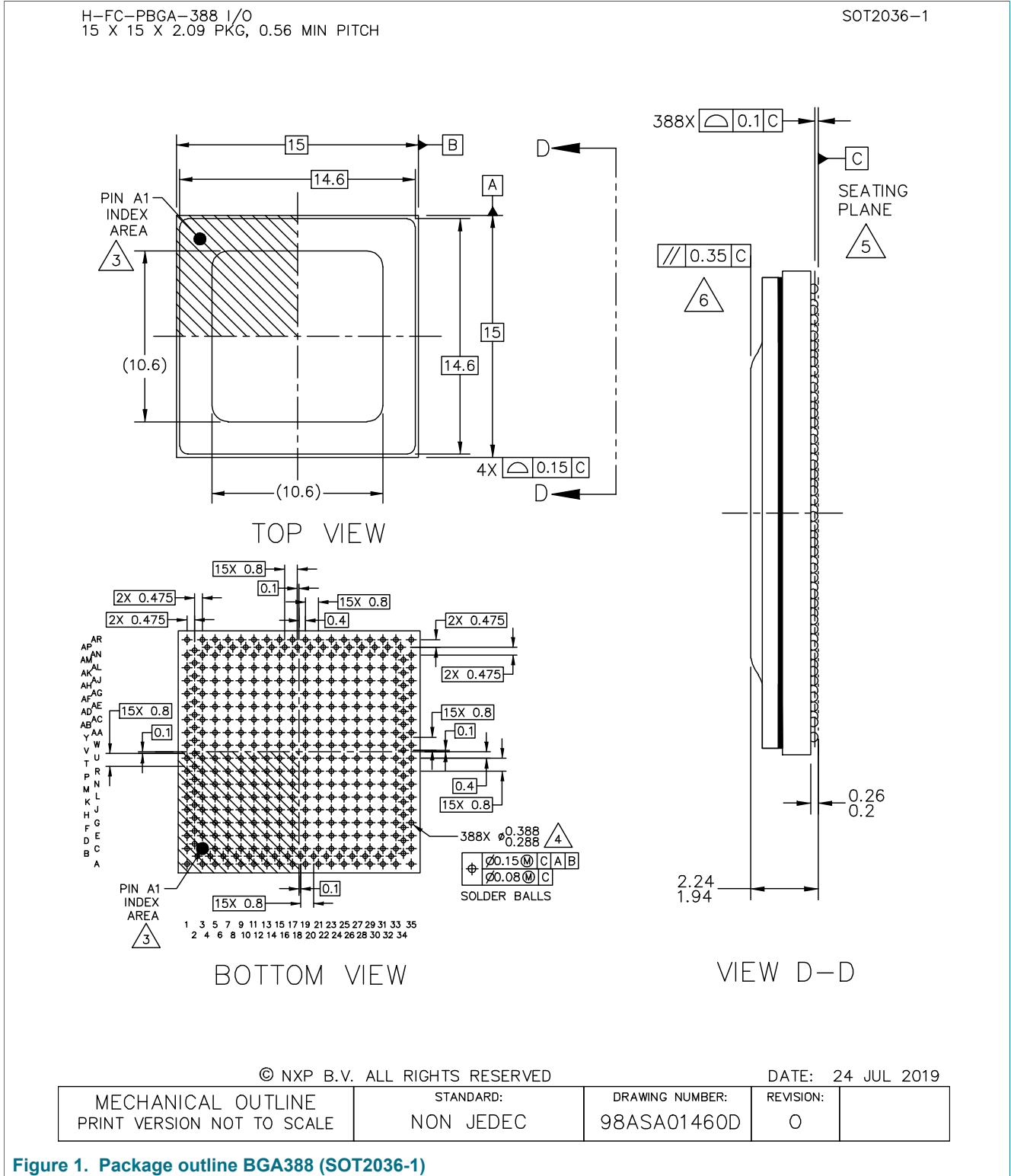


Figure 1. Package outline BGA388 (SOT2036-1)

3 Soldering

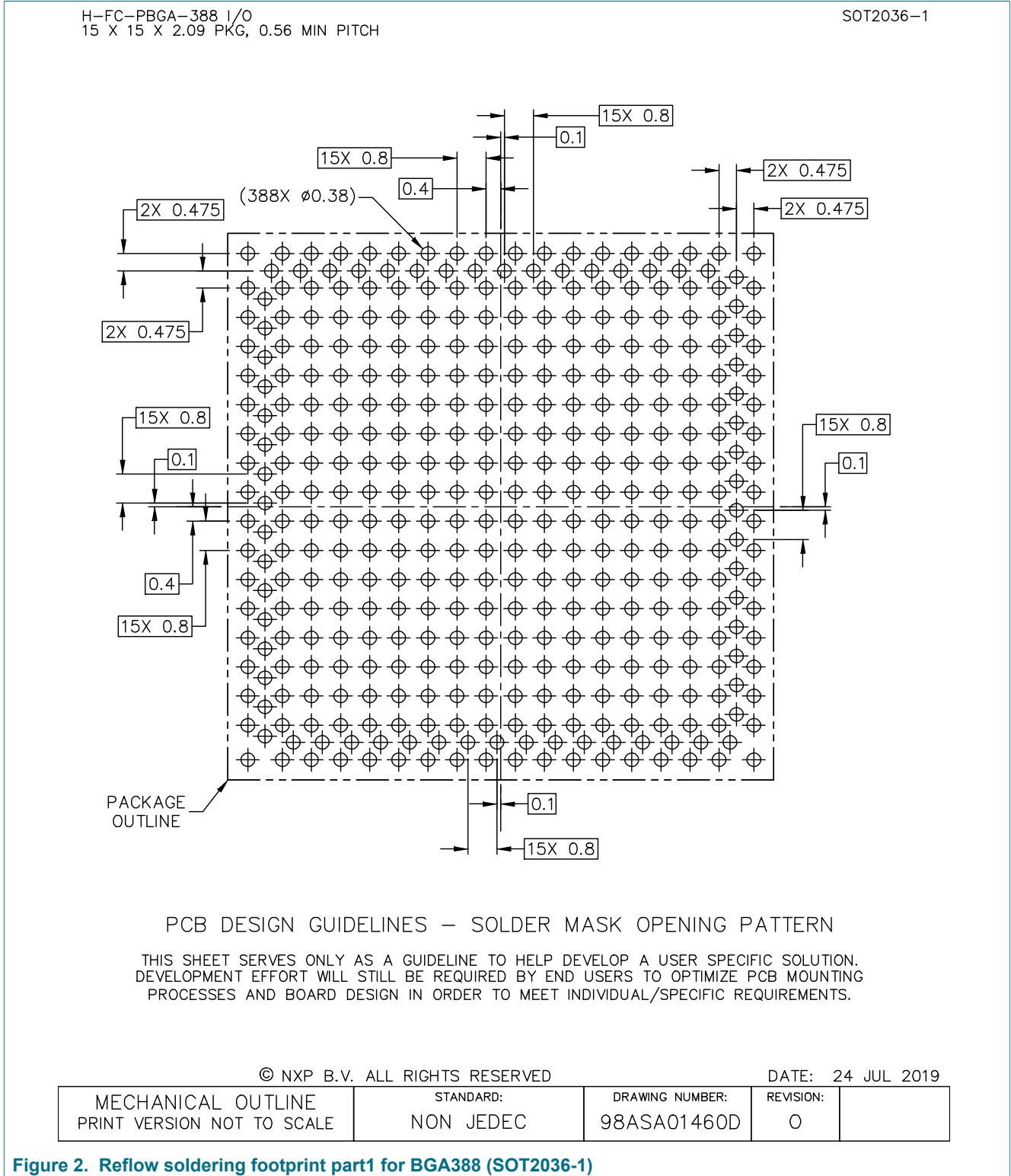


Figure 2. Reflow soldering footprint part1 for BGA388 (SOT2036-1)

BGA388, ball grid array package, 388 terminals, 0.56 mm pitch, 15 mm x 15 mm x 2.09 mm body

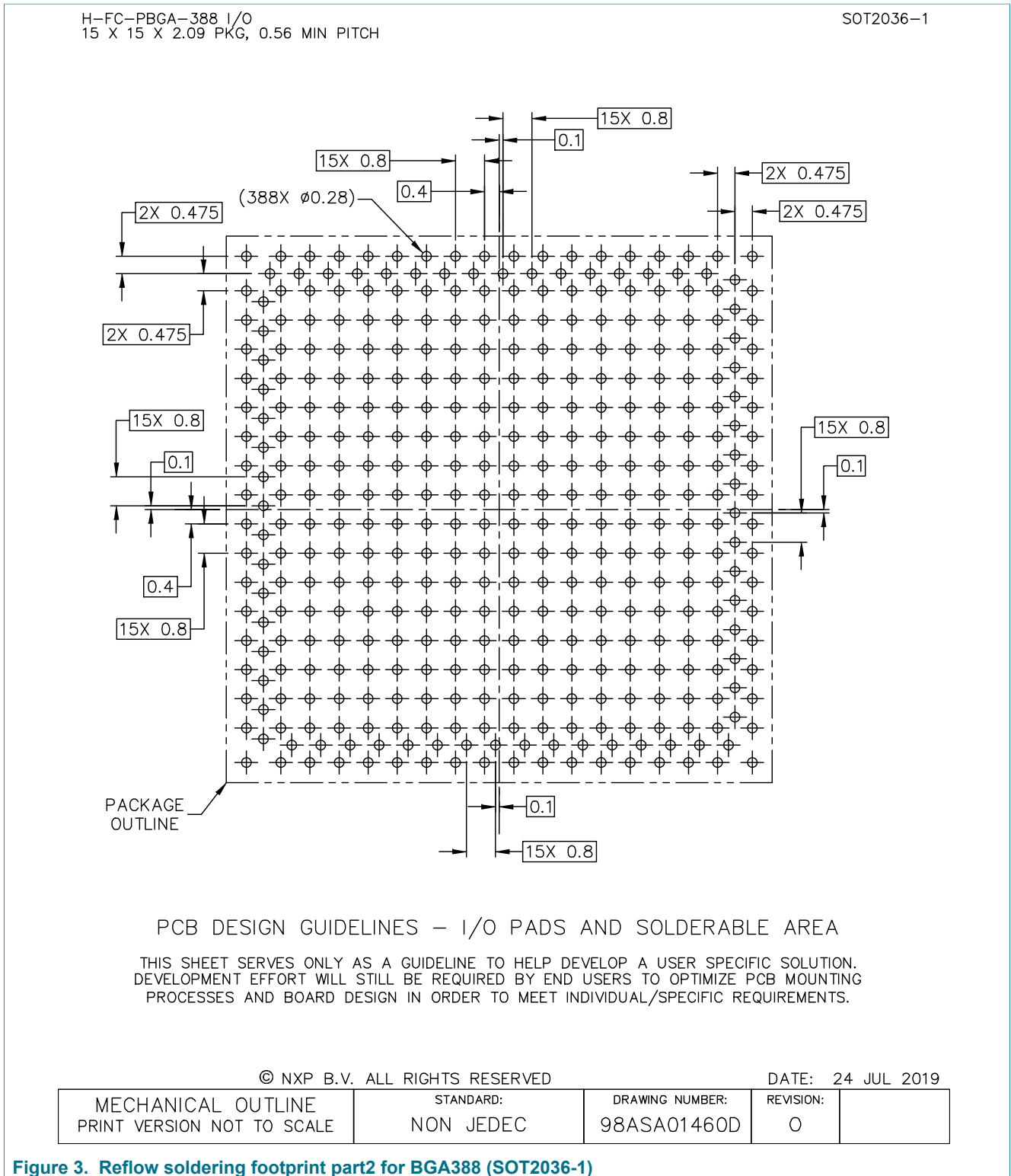
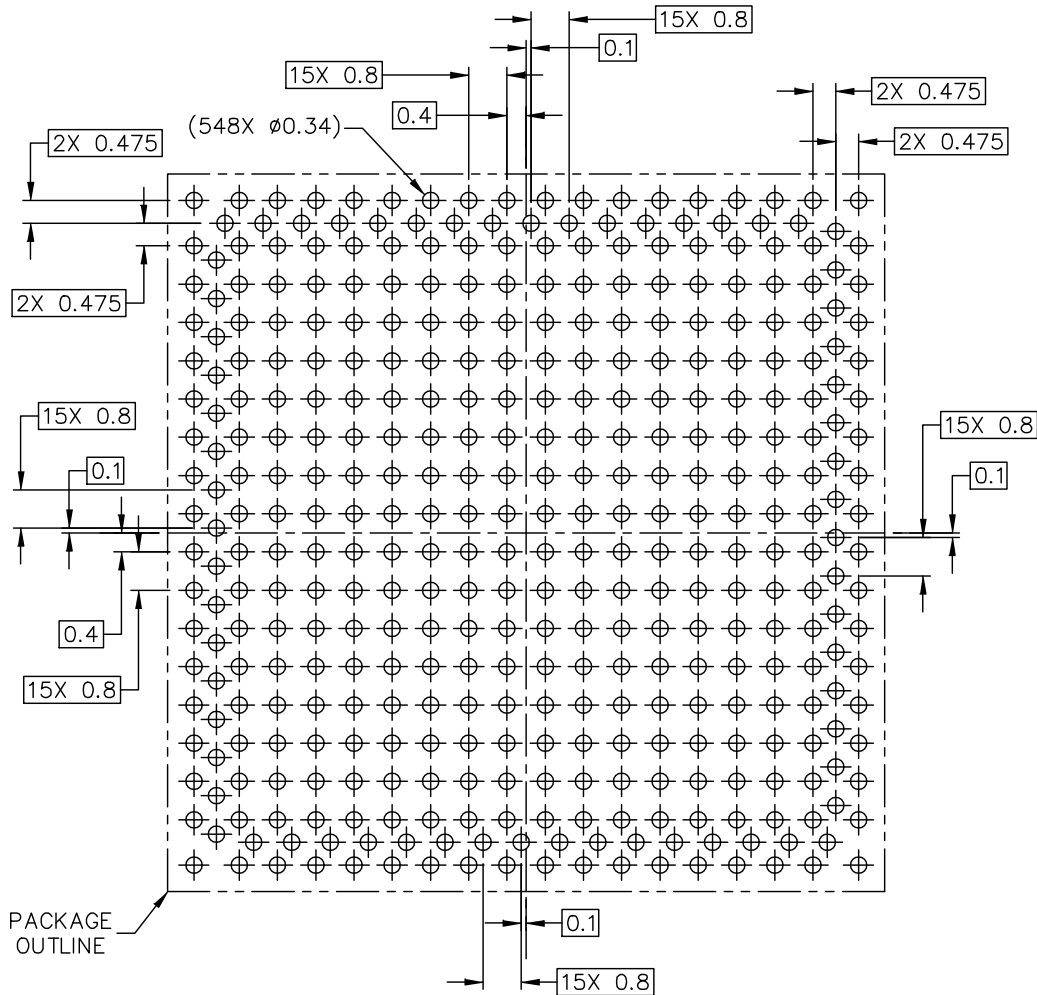


Figure 3. Reflow soldering footprint part2 for BGA388 (SOT2036-1)

BGA388, ball grid array package, 388 terminals, 0.56 mm pitch, 15 mm x 15 mm x 2.09 mm body

H-FC-PBGA-388 I/O
15 X 15 X 2.09 PKG, 0.56 MIN PITCH

SOT2036-1



RECOMMENDED STENCIL THICKNESS 0.125MM

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01460D	REVISION: O	
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Figure 4. Reflow soldering footprint part3 for BGA388 (SOT2036-1)

BGA388, ball grid array package, 388 terminals, 0.56 mm pitch, 15 mm x 15 mm x 2.09 mm body

H-FC-PBGA-388 I/O
15 X 15 X 2.09 PKG, 0.56 MIN PITCH

SOT2036-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
7. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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Figure 5. Package outline note BGA388 (SOT2036-1)

4 Legal information

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